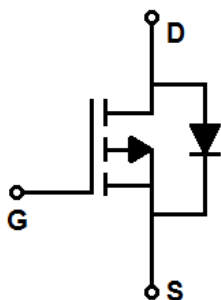
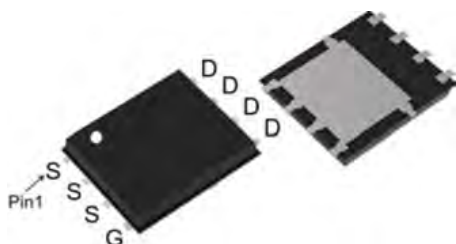


Trench P-channel Power MOSFET

MSR015P03D33
PDFN3*3



V_{DS}	-30	V
$R_{DS(on),TYP@ V_{GS}=10\text{ V}}$	11	m Ω
I_D	-10	A

Features

- 1、Low on – resistance
- 2、Package PDFN3*3
- 3、Trench P-channel Power MOSFET
- 4、Halogen free

Applications

- 1、Load Switch for Portable Devices
- 2、DC/DC Converter

Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter		Rating	Unit
V(BR)DSS	Drain-Source breakdown voltage		-30	V
VGS	Gate-Source voltage		±20	V
ID	Continuous drain current @VGS=10V	T _C =25°C	-10	A
		T _C =70°C	-8	A
IDM	Pulse drain current tested	T _C =25°C	-24	A
EAS	Avalanche energy, single pulsed		25	mJ
PD	Maximum power dissipation	T _C =25°C	3.3	W
TSTG,TJ	Storage and Junction Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	5.0	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	60	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
--------	-----------	-----------	------	------	------	------

Static Electrical Characteristics @ T_j=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	-30	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-24V, V _{GS} =0V	--	--	-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.2	--	-2.5	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-10A	--	11	15	mΩ
		V _{GS} =-4.5V, I _D =-8A	--	17	25	mΩ

Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V , f=1MHz	--	1200	--	pF
C _{oss}	Output Capacitance		--	155	--	pF
C _{rss}	Reverse Transfer Capacitance		--	139	--	pF
Q _g	Total Gate Charge	V _{DS} =-15V, I _D =-1A , V _{GS} =-10V	--	10	--	nC
Q _{gs}	Gate-Source Charge		--	2	--	nC
Q _{gd}	Gate-Drain Charge		--	2.7	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	V _{DS} =-15V, V _{GS} =-10V, R _G =6.0Ω, I _D =-1A	--	13	--	ns
Tr	Turn-on Rise Time		--	15	--	ns
Td(off)	Turn-Off Delay Time		--	198	--	ns
Tf	Turn-Off Fall Time		--	98	--	ns

Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)

I _{SD}	Source drain current(Body Diode)	T _A =25°C	-	-	-10	A
V _{SD}	Forward on voltage	I _{SD} =-10A, V _{GS} =0V	--	-	-1.2	V

Typical Characteristics

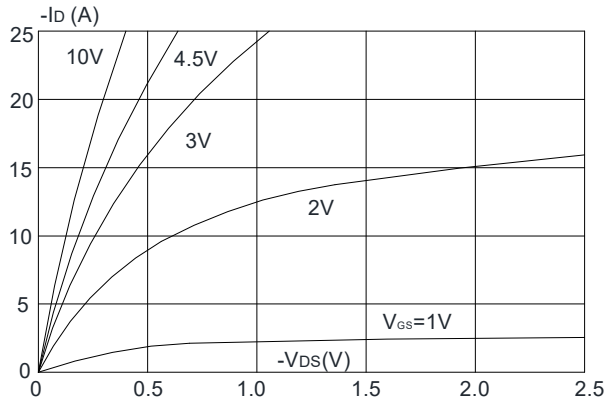


Figure 1: Output Characteristics

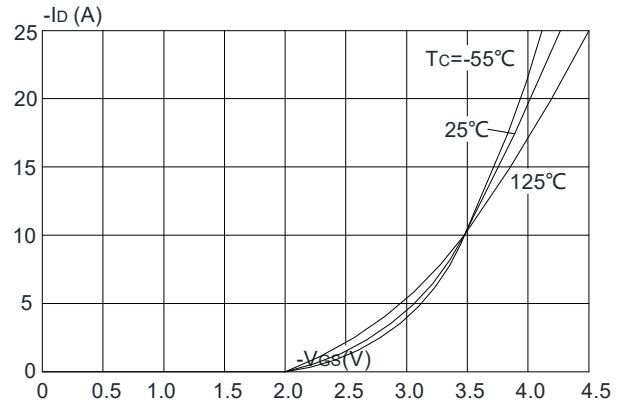


Figure 2: Typical Transfer Characteristics

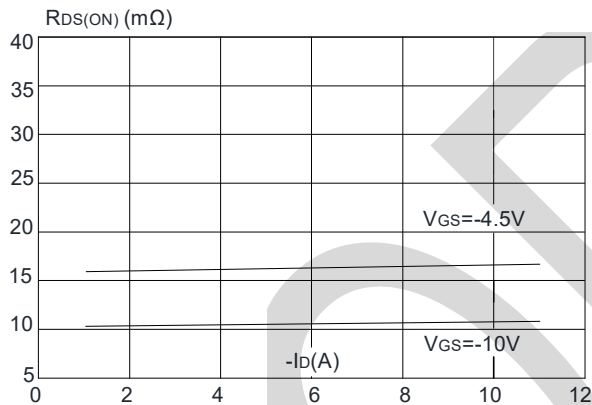


Figure 3: On-resistance vs. Drain Current

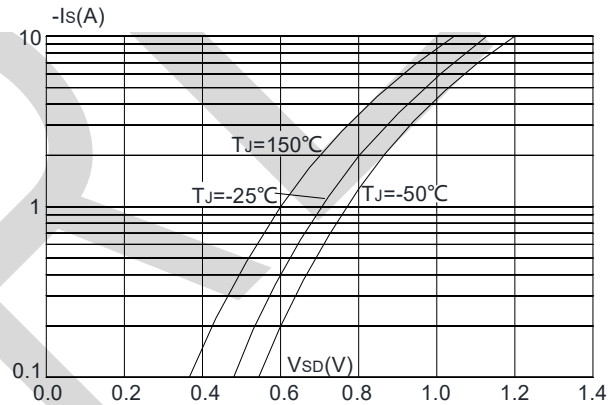


Figure 4: Body Diode Characteristics

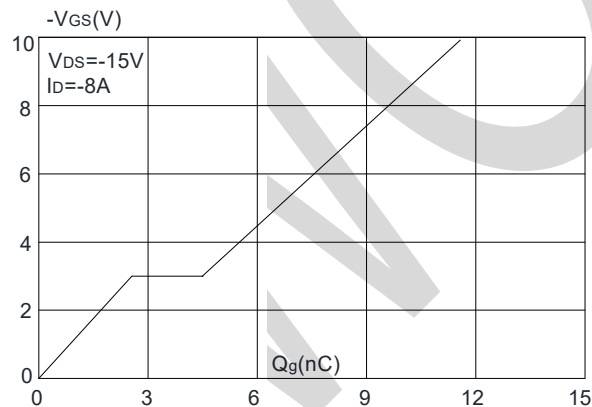


Figure 5: Gate Charge Characteristics

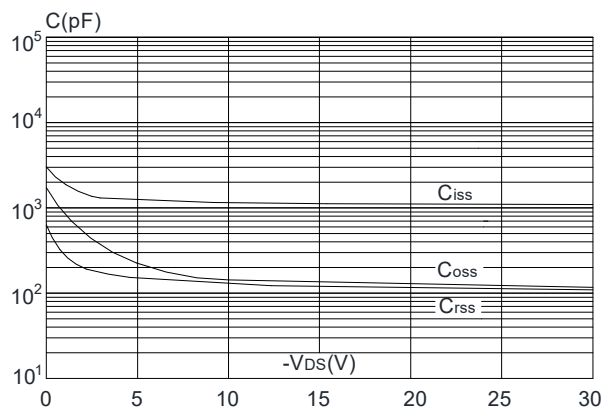


Figure 6: Capacitance Characteristics

Typical Characteristics

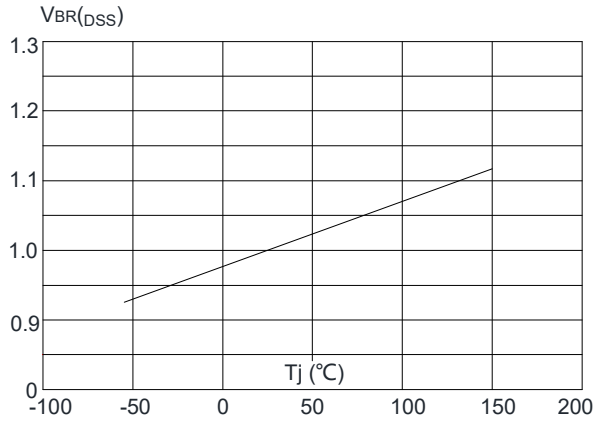


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

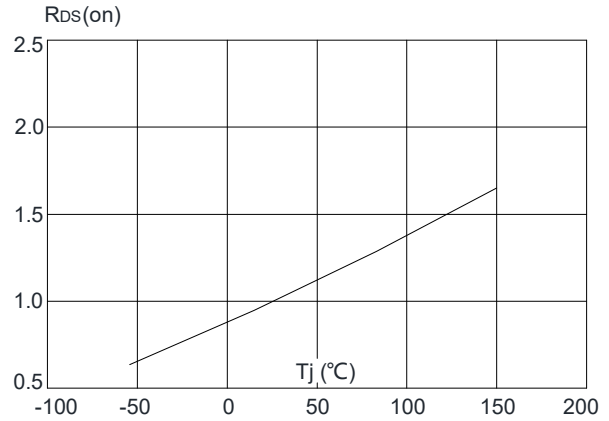


Figure 8: Normalized on Resistance vs. Junction Temperature

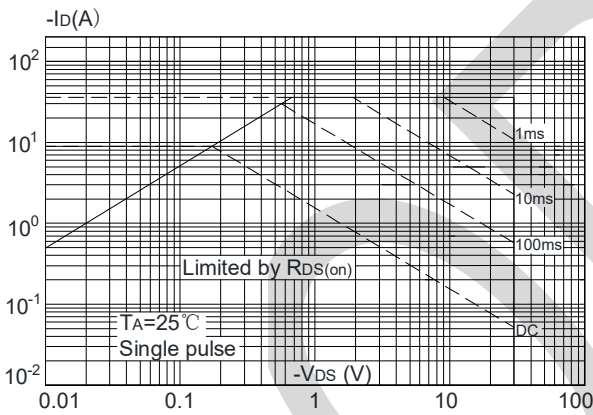


Figure 9: Maximum Safe Operating Area

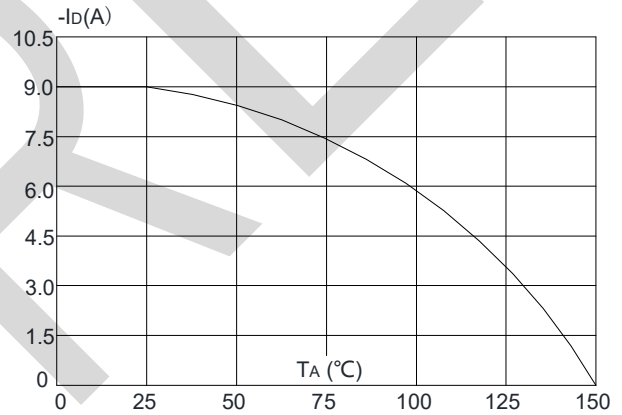


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

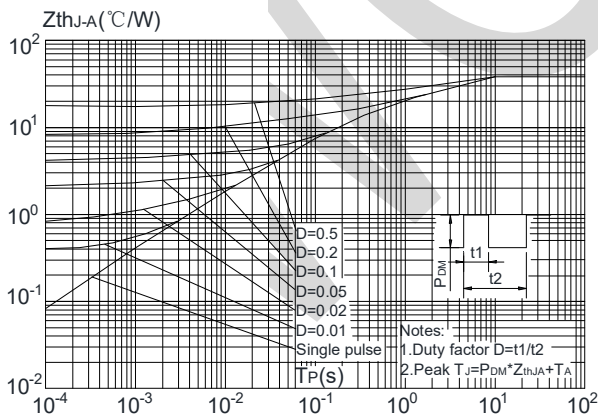
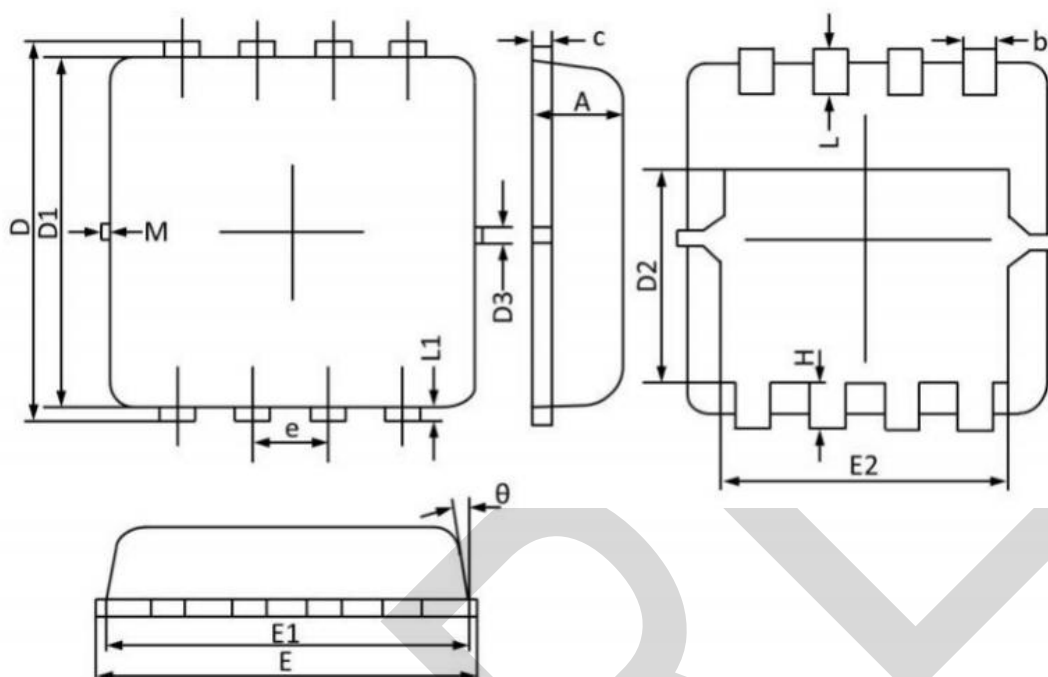


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

PACKAGE OUTLINE DIMENSIONS



unit : mm

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.75	0.80	b	0.25	0.30	0.35
C	0.10	0.15	0.25	D	3.25	3.35	3.45
D1	3.00	3.10	3.20	D2	1.78	1.88	1.98
D3	--	0.13	--	E	3.20	3.30	3.40
E1	3.00	3.15	3.20	E2	2.39	2.49	2.59
e	0.65BSC			H	0.30	0.39	0.50
L	0.30	0.40	0.50	L1	--	0.13	--
θ	--	10°	12°	M	*	*	0.15